

July 2016

Chip beads

For general signal line

HF-ACB series

HFxxACB2012 Type

HFxxACB2012 [0805 inch]*

* Dimensions code JIS[EIA]

Reminders for using these products

Before using these products, be sure to request the delivery specifications.

Safety reminders

Please pay sufficient attention to the warnings for safe designing when using this products.

<u> </u>
○ The storage period is less than 12 months. Be sure to follow the storage conditions (temperature: 5 to 40°C, humidity: 10 to 75% RH or less).
If the storage period elapses, the soldering of the terminal electrodes may deteriorate.
On not use or store in locations where there are conditions such as gas corrosion (salt, acid, alkali, etc.).
 Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
 Soldering corrections after mounting should be within the range of the conditions determined in the specifications. If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
When embedding a printed circuit board where a chip is mounted to a set, be sure that residual stress is not given to the chip due to the overall distortion of the printed circuit board and partial distortion such as at screw tightening portions.
Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
 Carefully lay out the coil for the circuit board design of the non-magnetic shield type. A malfunction may occur due to magnetic interference.
Use a wrist band to discharge static electricity in your body through the grounding wire.
On not expose the products to magnets or magnetic fields.
On not use for a purpose outside of the contents regulated in the delivery specifications.
The products listed on this catalog are intended for use in general electronic equipment (AV equipment, telecommunications equipment, home appliances, amusement equipment, computer equipment, personal equipment, office equipment, measurement equipment, industrial robots) under a normal operation and use condition. The products are not designed or warranted to meet the requirements of the applications listed below, whose performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society,
person or property.

- (1) Aerospace/aviation equipment
- (2) Transportation equipment (cars, electric trains, ships, etc.)
- (3) Medical equipment
- (4) Power-generation control equipment

set forth in the each catalog, please contact us.

- (5) Atomic energy-related equipment
- (6) Seabed equipment
- (7) Transportation control equipment

- (8) Public information-processing equipment
- (9) Military equipment
- (10) Electric heating apparatus, burning equipment
- (11) Disaster prevention/crime prevention equipment
- (12) Safety equipment
- (13) Other applications that are not considered general-purpose applications

When designing your equipment even for general-purpose applications, you are kindly requested to take into consideration securing protection circuit/device or providing backup circuits in your equipment.

If you intend to use the products in the applications listed below or if you have special requirements exceeding the range or conditions

EMC Components



Chip beads

For general signal line

Product compatible with RoHS directive
Halogen-free
Compatible with lead-free solders

Overview of HFxxACB2012 type

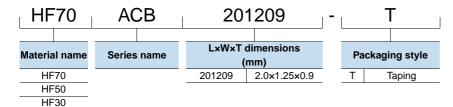
FEATURES

- O Noise reduction solution for general signal line.
- Achieves various frequency characteristics by using 3 materials with different features.
- O There is no directivity.

APPLICATION

Signal line noise removal for DSCs, DVCs, PCs, TVs, printers, game machines, smart grids, wireless base stations, industrial equipment.

■ PART NUMBER CONSTRUCTION



■ OPERATING TEMPERATURE RANGE, PACKAGE QUANTITY, PRODUCT WEIGHT

	Temperati	ire ranges	Package quantity	Individual weight
Туре	Operating	Storage		
	temperature	temperature*		
	(°C)	(°C)	(pieces/reel)	(mg)
HFxxACB2012	-40 to +125	-40 to +125	2,000	10

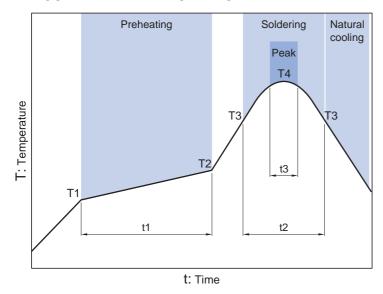
^{*} The storage temperature range is for after the circuit board is mounted.

RoHS Directive Compliant Product: See the following for more details.https://product.tdk.com/info/en/environment/rohs/index.html

O Halogen-free: indicates that CI content is less than 900ppm, Br content is less than 900ppm, and that the total CI and Br content is less than 1500ppm.



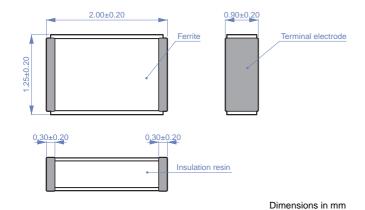
■ RECOMMENDED REFLOW PROFILE



Preheating Soldering Peak Time Temp. Time Time Temp. Temp. t3 180°C 60 to 120s 250 to 260°C 150°C 30 to 60s 230°C 10s

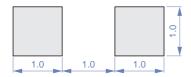


■SHAPE & DIMENSIONS





■ RECOMMENDED LAND PATTERN



Dimensions in mm



ELECTRICAL CHARACTERISTICS

CHARACTERISTICS SPECIFICATION TABLE

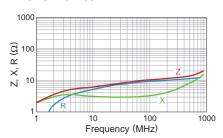
Impedance		DC resistance	Rated current	Part No.
[100MHz]				
(Ω)	Tolerance	(Ω)max.	(mA)max.	
10	±25%	0.1	600	HF70ACB201209-T
11	±25%	0.1	600	HF50ACB201209-T
7	±25%	0.1	600	HF30ACB201209-T



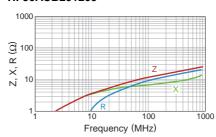
ELECTRICAL CHARACTERISTICS

□Z, X, R VS. FREQUENCY CHARACTERISTICS

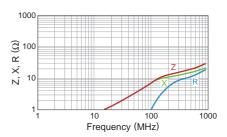
HF70ACB201209



HF50ACB201209



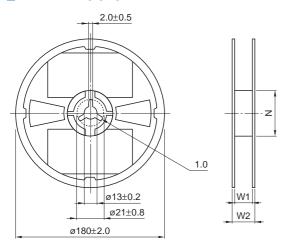
HF30ACB201209





■PACKAGING STYLE

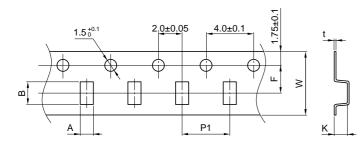
REEL DIMENSIONS



Type	W1	W2	N
HFxxACB2012	8.4+2.0/-0.0	14.4max.	ø60min.

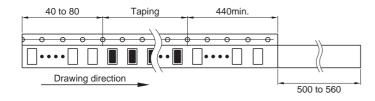
Dimensions in mm

TAPE DIMENSIONS



Dimensions in mm

Туре	Α	В	F	P1	W	K	t
HFxxACB2012	1.4±0.1	2.25±0.1	3.5±0.05	4.0±0.1	8.0±0.3	1.25max.	0.3max.



Dimensions in mm